



Material Content Data Sheet



Sales Product Name		1EDI30I12MF		Issued		27. September 2017			
MA#		MA001246590							
Package		PG-DSO-8-51		Weight*		80.28 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.769	2.20	2.20	22038	22038	
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		103		
	non noble metal	zinc	7440-66-6	0.033	0.04		411		
	non noble metal	iron	7439-89-6	0.660	0.82		8218		
wire	non noble metal	copper	7440-50-8	26.789	33.37	34.24	333696	342428	
	noble metal	gold	7440-57-5	0.228	0.28	0.28	2845	2845	
	encapsulation	organic material	carbon black	1333-86-4	0.148	0.18		1838	
plastics	plastics	epoxy resin	-	4.772	5.94		59435		
	inorganic material	silicondioxide	60676-86-0	44.272	55.17	61.29	551458	612731	
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10137	10137	
plating	noble metal	silver	7440-22-4	0.095	0.12	0.12	1186	1186	
glue	plastics	acrylic resin	-	0.153	0.19		1900		
	noble metal	silver	7440-22-4	0.541	0.67	0.86	6735	8635	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com